

# plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped)

6 September 2016

**Package information** 

### 1. Package summary

Dimensions (mm)11 x 10 x 4.3Terminal position codeS (single)Package type descriptive codeD2PAKPackage outline version codeSOT404AManufacturer package codeSOT404Package type industry codeD2PAK

Package outline version description plastic single-ended surface-mounted package

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Package style descriptive code SMS
Package body material type P

Handling precautionsIC26\_CHAPTER\_3\_2000Thermal design considerationsSC18\_1999\_CHAPTER\_5\_2

Mounting method type S (surface mount)

Generic mounting and soldering information SC18\_2004\_CHAPTER\_4\_3

Major version date28-2-2013Minor version date6-9-2016

Security status COMPANY PUBLIC

Modified date28-2-2013Issue date12-3-2013Web publication date28-2-2013Initial web publication date28-2-2013

Customer specific indicator N

Maturity Product

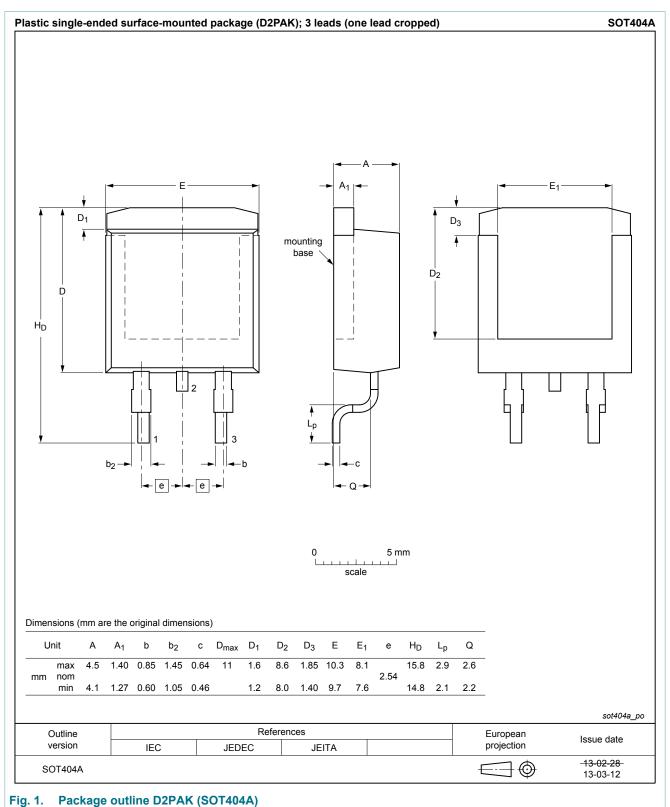
#### Table 1. Package summary

Symbol	Parameter	Min	Тур	Nom	Max	Unit
A <sub>2</sub>	package height	-	-	-	-	mm
Α	seated height	4.1	-	4.3	4.5	mm
D	package length	-	-	11	11	mm
E	package width	9.7	-	10	10.3	mm
е	nominal pitch	-	-	2.54	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	3	-	



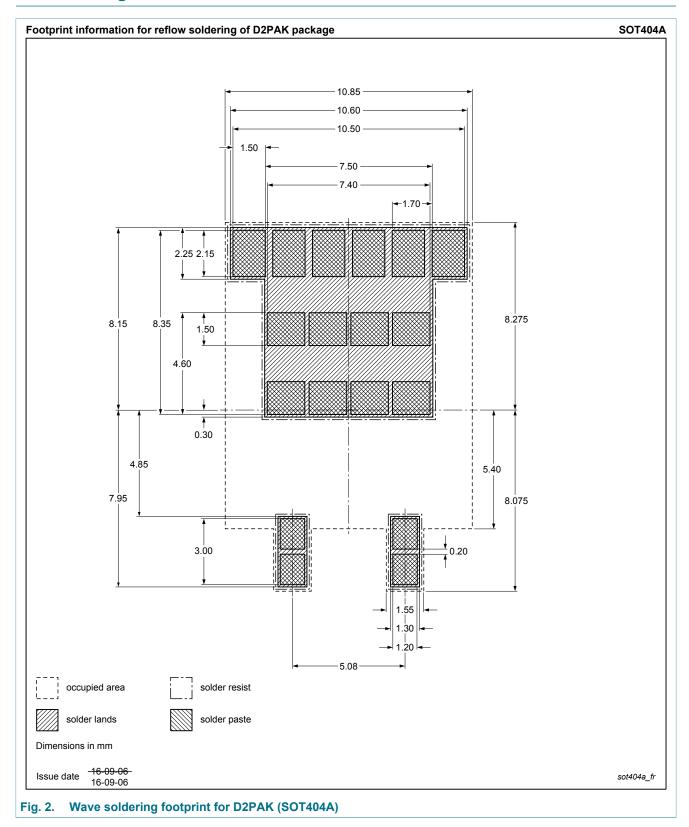
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# 2. Package outline



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# 3. Soldering



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#### 4. Legal information

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